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# Computer Architecture

CS/ECE 6810

## Today's topics:

- course logistics & motivation
- computer architecture as a profession
- market segments
- technology scaling and cost

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# Introductory Material

- **A few tidbits on the instructor**
- **Pay close attention to the course web page**
  - <http://www.eng.utah.edu/~cs6810>
  - it will change so keep up to date on what's there
- **Why study computer architecture?**
  - **It's required for CS grad students**
    - » **OK I get that but will try to make it interesting anyway**
  - **for SW types:**
    - » **understanding the architecture → maximize code performance**
  - **for HW types:**
    - » **essential understanding for the profession**
  - **rich area where contributions are badly needed**
    - » **one of which might be your thesis**
  - **current state of the art is in a wild time**
    - » **architecture changes directions – see “badly needed”**
    - » **lots of job opportunities**

## Artifacts of Rapid Change

- **Textbook**

- **4<sup>th</sup> edition is significantly more relevant than previous versions**
  - » **BUT it's now 2-3 years old and a lot has happened**
  - » **result: lectures will have some disagreements w/ the text**
    - reading the book will be necessary
    - attending the lectures will hopefully also be valuable
- **the basic issues in the text are still important**
  - » **bulk of course will focus on this material**
- **tons of research literature**
  - » **not a requirement in this course but helpful to clarify or deepen your understanding**
  - » **the Internet is your friend**
    - as is the University's subscription to digital libraries
      - IEEE Xplore is probably the most useful
      - ACM is a good 2<sup>nd</sup> choice

## Computer Architecture

- **Strictly speaking – it's a whole system thing**

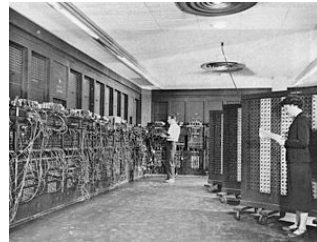
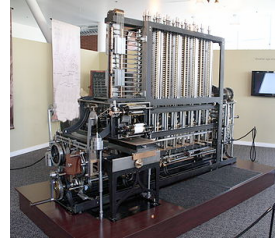
- **study of the structure of computer hardware**
  - » **requires a diverse set of systems & circuit understanding**
    - languages & operating systems
    - high level organizational issues (our focus in CS6810)
      - processor, cache, main memory, I/O, networking/interconnect, storage
    - analysis via tools such as simulation
      - power, performance, energy efficiency, verification
    - transistor circuits, wires, and fabrication technology
    - layout, EDA tools, cooling, packaging, ...
  - » **you can't be a wizard in one of these areas**
    - without understanding the constraints and interfaces imposed by the other disciplines

- **The profession:**

- **Industry: design & build the systems of the future**
  - » **often w/ large teams of specialized wizards**
- **academic: study and explore new directions**
  - » **few actually build things except as models via simulation**

## A Snippet of Modern History

- **Mechanical difference engine**
  - proposed in 1786 by J. H. Mueller
  - 2 versions built by Charles Babbage in the 1820's
    - » image at right is a replica in the computer museum in Mtn. View, CA
- **Electronic computer**
  - WW2: army needed something to compute ballistics tables
  - contract w/U Penn in 1943
  - operational in 1946
    - » analog machine
    - » programmed by plugging cables into the right spot
    - » YOW!!
  - numerous analog machines follow
    - » vacuum tubes, crystal diodes, ...



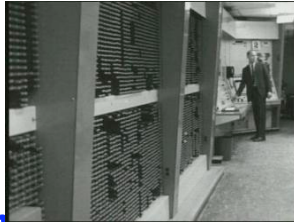
## History II

- **Stored program computer**
  - Concept: EDVAC report 1945 by John von Neumann
    - » hence the von Neumann architecture tag
  - Implementation
    - » Jun 1948 – Manchester Univ. experimental machine
      - “Baby” SSEM (small scale experimental machine)
      - memory = Williams Cathode Ray Tubes
    - » First practical: EDSAC May 1949 (also done in the UK)
      - memory = delay-lines



## Then Came Transistors ...

- **First all transistor computer**
  - MIT's Linc, TX-0, TX-2 – Wes Clark 1950's
    - » led to networks, graphics, interactive computing

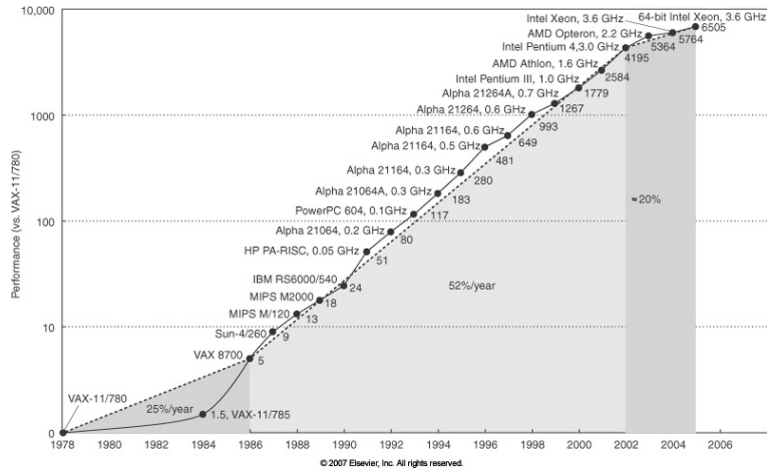


- **Integrated circuit**
  - more than one transistor on a die – 1958
    - » Rob't Noyce and Gordon Moore @ Fairchild
      - later founders of Intel
  - first microprocessor Intel 4004 in 1971
    - » 10 um pMOS, 92 Kips, 740 KHz, 4-bit data-path, BCD
      - » it's been a wild ride ever since



## Unprecedented Improvement

- **Moore's surprising prediction in 1965 holds up**
  - reasonably well so far



## CAGR Inflection Points

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- **Improvement**
  - consistent technology gain
  - architecture less consistent
- **Inflection points**
  - **1<sup>st</sup> 25 years: 25% due to both**
  - **late 70's uProcessors emerge**
    - » 35%
    - » + 17% from architecture
      - RISC, pipelining, ILP and multiple issue (a.k.a. super scalar)
    - » 16 years of Moore's law growth
  - **2002 things slow to ~20%**
    - » 3 key hurdles: thermals, insufficient ILP, slow memory
      - DRAM improvement trends: CAGR = 7%
        - latency hiding worked well until 2002
  - **New agenda: TLP and DLP**
    - » enter multi-threading and multi-core architectures

## Computer Classes/Market Segments

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- **Note**
  - today all classes are microprocessor based
    - » not all microprocessors are the same
      - even when they appear to be the same to the programmer
  - also my classes are quite different than the text's
- **Embedded (fastest growth segment)**
  - huge range: automotive, cell phones, ... large internet switches → specialization
    - » CISCO EPS-1 already contains 192 core
    - » processors vary:
      - 4- 64-bit processors
        - price from a few cents to a few hundred dollars
        - system cost from \$1 to \$1M
    - » typical differentiation
      - typical user tends to not be the programmer
        - provides a relatively fixed function or service
      - hard or soft real time performance often required

## Segments (cont'd)

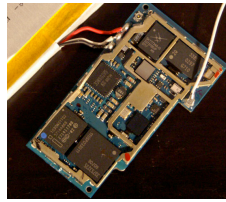
- **Netbook**
  - **cheap, light, and a bigger screen than a cell phone**
    - » **battery life is a key issue**
      - **processor performance compromised for energy efficiency**
- **Laptop**
  - **a bit heavier and more expensive**
    - » **more diversity in performance and energy efficiency than netbook**
    - » **processor and system cost: 2-5x netbook**
- **Desktop**
  - **market rapidly slowing due to netbook, laptop, and server expansion**
    - » **with a network the screen, keyboard, and compute gizmo's need not be co-located**
    - » **diverse motherboard capability (performance, memory, etc.)**
    - » **\$50 - \$1000 processor, 5-10x more for system**

## Big Iron Segments

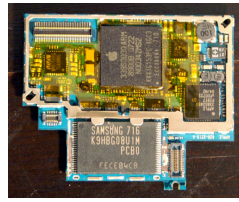
- **Key additional difference**
  - **high enhanced**
    - » **interconnect, main memory, and storage subsystems**
- **Compute servers**
  - **usually a cluster of racks**
    - » **holding blades**
      - **similar to desktop motherboard**
    - » **lots of choices for storage subsystem**
- **Datacenter/Warehouse**
  - **very large cluster of racks**
    - » **system cost from \$100K to \$10'sM**
    - » **redundant everything for high availability**
    - » **e.g. Google or the "Cloud"**
- **Supercomputer (single customer type, FPU focus)**
  - **check out the top 500 list: <http://top500.org>**
  - **system cost \$10-100M**

## Addendum: Complex Embedded Systems

- **Key characteristic**
  - **some things programmable and some things not**
    - » **not: ASIC or IP blocks**
- **Example: iPhone**
  - **Single programmable ARM core**
    - » **Integrated with ~50 IP blocks**
      - **each block is highly specialized (multiple blocks/chip)**
        - ~100x Improvement in energy-delay product



Cell Phone Part



Computer Part

Source: Anandtech

## Computer Architecture

- **Focus issues for CS6810**
  - **3 key components**
    - » **ISA (2 lectures from now – Appendix B)**
    - » **Organization**
      - **high level structural aspects of various subsystems**
        - pipeline structure
        - function unit structure
        - processor structure
        - cache hierarchy structure
        - main memory structure
        - I/O & network interface
      - **note there are other subsystems that we'll get to in the 2<sup>nd</sup> half**
        - interconnect structure
        - storage structure and technologies
    - » **Hardware (only light coverage here)**
      - **logic design, process, packaging, cooling, timing, wires ...**
        - this is an almost endless list
        - VLSI courses in analog and digital IC design should be next
          - If you intend to live on the HW side of architecture

## Intent of the Course

- **Provide a foundation for future professional activity**
  - **at least 3 possible goals**
    - » **understanding the compute platform that you use**
      - key to achieving highly efficient code for SW types
      - ISA and organization are what you care about
    - » **research into new architectural options**
      - key academic role & possible thesis area preparation
      - ISA, organization, and high level understanding of hardware constraints will be needed
    - » **design of new systems**
      - perhaps the ultimate relevance
      - further courses will be needed to finish this process
        - VLSI & embedded systems courses will be your next step
      - all 3 will be important
        - in much greater depth
- **OK that's the sales pitch**
  - **for why you should care**

## Tracking Trends

- **Fast moving arena & lengthy design process**
  - **typical 5-year design schedule**
    - » **typical design team ~500 engineers**
    - » **year 1: architectural concept and simulation infrastructure development**
    - » **year 2: architectural optimization, validation**
      - architecture freeze at the end of year 2
    - » **year 3 & 4: circuit design, floor-planning, and packaging**
      - tape out at the end of year 4
    - » **year 5**
      - refine process to achieve acceptable yields
      - test and validate fab'd chips
      - build inventory since volume sales commence
- **Note**
  - **you need to design for a technology that doesn't exist when the design phase starts**
  - **need to accurately predict what will be available**



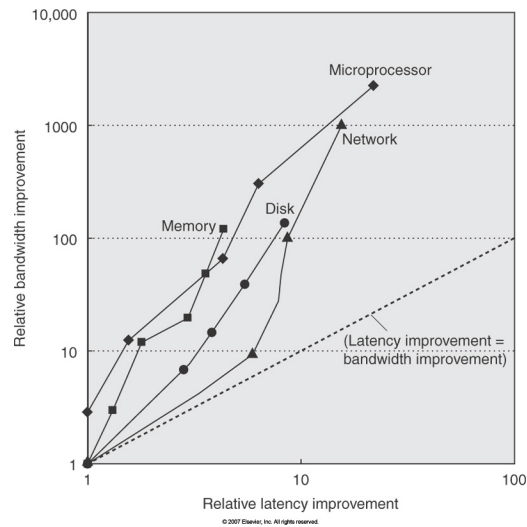
## Technology Trends

- **VLSI**
  - **transistor density improves 35%/yr**
    - » **due to process shrink**
      - **there are some hidden dragon's here**
  - **die size increases by 10-20%/yr**
  - **transistor budget/chip increases 40-55%/yr**
    - » **today the limit is power rather than # of T's (more on this later)**
- **DRAM**
  - **capacity increases 40%/yr**
    - » **access latency increases at only 7%/yr however**
- **Disks get better in steps:**
  - **capacity CAGR ranges from 30% - 60%**
    - » **we're back to 30% now**
  - **latency virtually unchanged (for MHD's ~10ms)**
    - » **bandwidth significantly better however**
    - » **SSD's now on the scene with much better latency than MHD's**

## Performance

- **Bandwidth vs. Latency**
  - **bandwidth is associated with throughput**
  - **latency is the response time for a single transaction**
- **Usually you care about how fast your job runs**
  - **for any job that takes more than a few seconds**
  - **also depends on market segment**
    - » **latency critical for real time constraints**
    - » **throughput critical for data-center or supercomputer apps**
      - **but your personal computer runs lots of processes too**
      - **tends to bias throughput importance**
- **Power wall has changed the industry to throughput**
  - **killer uP is now dead as is single thread performance**
    - » **Intel cancels Tejas in 2004**
  - **TLP, DLP, and multi-core**
    - » **throughput centric will persist (exception is embedded segment)**

## Bandwidth Optimization Results



## IC Scaling

- **As feature size  $\lambda$  goes down**
  - **transistor speed scales as  $1/\lambda$**
  - **wire speed scales as  $\alpha RC$** 
    - » **as wires get smaller – cross section decreases, R increases**
      - aspect ratio changing somewhat to compensate
      - wires do not shrink as much as T's
    - » **C goes down but not linearly**
      - plate C improves but sidewall is an issue
      - sidewall C can be improved with process
        - low-K dielectric and hot-wire air gap today
    - » **wire speed for unrepeated wires is quadratic with length**
      - proper repeater spacing makes wire delay roughly linear
      - at the expense of increased power for the repeaters
- **Key result**
  - **wires are the problem (Ron Ho's PhD thesis is a great read)**
    - » increasing contribution to power
    - » scaling poorly w.r.t. transistors

## IC Process

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- **ITRS is a predictor**
  - **industry consortium**
    - » **articulate what's needed to stay on Moore's curve**
      - **2x transistor count improvement every 2 years**
      - **1/sqrt(2) = .707**
    - » **<http://itrs.net>**
      - **look for the 2008 update**
  - **it's not strictly accurate but a good predictor**
    - » **Intel has recently pushed up the pace**
- **History (check out that .7 factor)**
  - **1997: 250nm**
  - **1999: 180nm**
  - **2001: 130nm**
  - **2003: 90 nm**
  - **2005: 65 nm**
  - **now: 45 nm**

## The End of Silicon

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- **When is the question**
  - **nothing lasts forever**
    - » **at some point the shrink will mean a transistor's components will be smaller than a silicon atom**
      - **clearly this can't work**
  - **glass half full or empty predictions vary**
    - » **some see the sky falling now**
    - » **others say we can get to 6 or 7 nm**
      - **but only if some current "unsolvables" get solved**
- **What's the alternative**
  - **DNA soup**
  - **quantum computing**
  - **bigger problems or a solution – you choose**
- **For now and the foreseeable future**
  - **silicon and CMOS**
    - » **several silicon varieties: strained, SOI, ...**

## Power Fundamentals

- **2 components:**
  - active – power consumed when something is happening
  - leakage – power consumed independent of activity
  - $P_{\text{total}} = P_{\text{active}} + P_{\text{leakage}}$
- **Pactive =  $\alpha CV^2f$** 
  - hence linear with frequency
- **Pleakage goes up 10x with every process step**
  - process & circuit tricks have mitigated this significantly
    - » how many one-trick ponies are in the stable
  - additional ~2x w/ every 10 C temperature dependence
    - » also dependent on Vdd-Vth
    - » actual equation is quite hairy
- **Voltage scaling**
  - quadratic benefit for  $P_{\text{active}}$
  - problem for  $P_{\text{leakage}}$
  - today there is little room for Vdd scaling

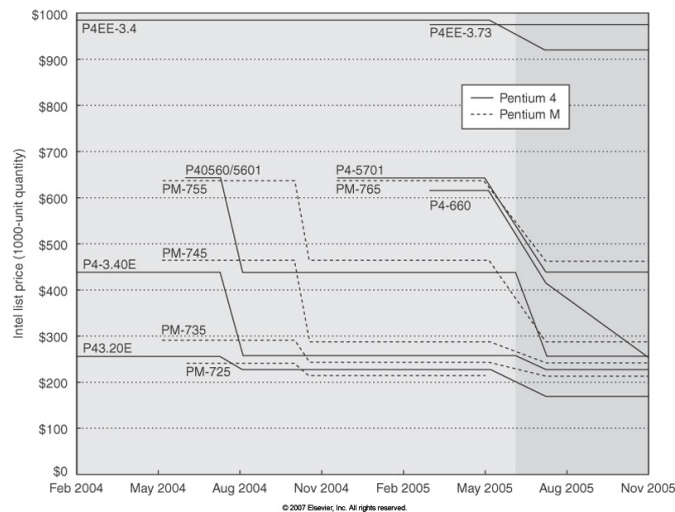


## Cost

- **Affected by market, technology, and volume**
  - WCT (whole cost transfer) varies w/ volume
    - » tooling and fabrication set up is very expensive
    - » fab line cost scales as  $(1/\lambda)^2$
- **Not that simple – what kind of cost?**
  - cost to buy – this is really price
  - cost to maintain
  - cost to upgrade – never known at purchase price
  - cost to learn to use – Apple won this one for awhile
  - cost of ISV software
  - cost to change platforms – vendor lock not dominant today
  - cost of a failure – Pandora's box
    - » see availability cost table Fig. 1.3 in your text
- **Let's focus on hardware costs**
  - it's simpler



## Learning Curve: Process Matures



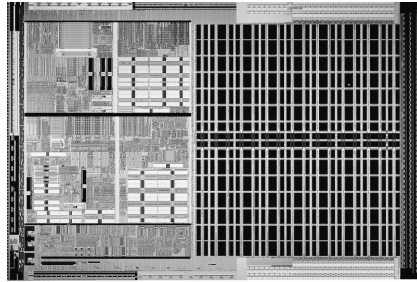
## Cost of an IC

- **More integration → IC is bigger piece of the total**

$$\text{IC-cost} = \frac{\text{Die-cost} + \text{Die-test-cost} + \text{Die-package-cost}}{\text{Final-Test-Yield}}$$

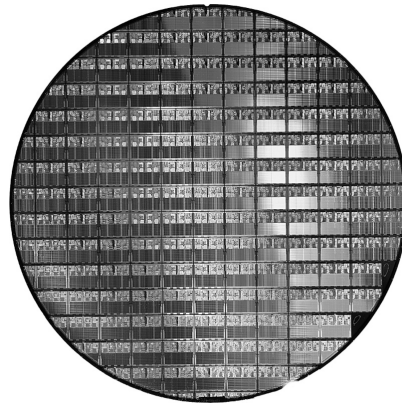
- **DRAM prices have very small margins**
  - range from \$20/die until end of life at ~\$2
  - » DRAM die are put on DIMMs (8 -19/Dimm)
  - » you buy DIMMs
- **IC's traditionally 25-50% of WCT for desktop box**
  - monitors and external disks may actually dwarf this cost
  - depends on system

## Wafers vs. Chips



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Dual Core Opteron



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117 Opteron Wafer  
90nm

## Die Cost

$$\text{Cost-of-die} = \frac{\text{Cost-of-wafer}}{\text{Dies-per-wafer} \times \text{Die-yield}}$$

$$\text{Dies-per-wafer} = \frac{\pi \times (\text{Wafer-diameter}/2)^2}{\text{Die-area}} - \frac{\pi \times \text{Wafer-diameter}}{\sqrt{2} \times \text{Die-area}} - \text{Test-dies-per-wafer}$$

square peg in round hole term

$$\text{Die-yield} = \text{Wafer-yield} \times \left( 1 + \left( \frac{\text{Defects-per-unit-area} \times \text{Die-area}}{\alpha} \right) \right)^{-\alpha}$$

- $\alpha$  depends on process
  - good estimate for  $\alpha$  in 2006 is 4.0
- defects are very rare these days
  - yield is very near 100% on a mature process

## Concluding Remarks

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- **It's important to keep several things in mind when a design decision is made**
  - **cost and area issues**
  - **totally new means new verification tactics**
    - » **an increasing component of design cost**
  - **power and performance trade-off**
- **What's the right metric**
  - **depends on what you care about**
  - **ideally you want more performance & less power for the work that you care about**
- **Note**
  - **power is an instantaneous, work independent metric**
  - **consider**
    - »  **$Q = \text{energy} \times \text{delay}^n$  (more realistic measure of design quality)**
    - » **adjust n for your bias**
      - **embedded n=1 typical, n=2 often used for performance oriented systems**